



MMC560x-B Prototyping Board

MMC560x-B

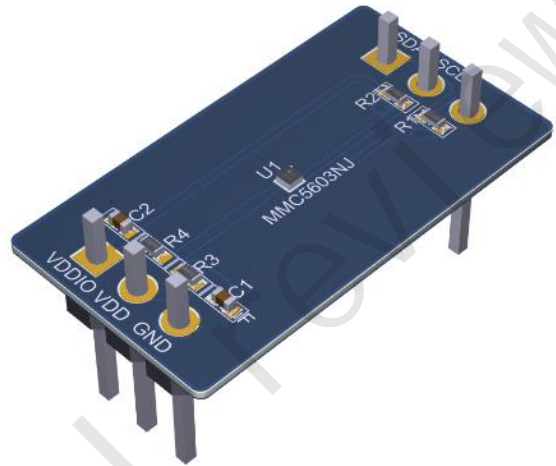
GENERAL DESCRIPTION

The MMC560x-B provides a convenient and easy way to evaluate and prototype with MMC560x the three axes magnetic sensor. The magnetic sensor and passive components needed for operations are SMT mounted on the board. Communication, power and ground pins of the MMC560x SMT device are brought out to standard 0.10 inch on center connections on the sides of the prototyping board. Wires can either be soldered directly to the prototyping board or DIP pins can be used with widely available breadboard kits.

For complete performance specifications of MMC560x refer to MMC560x datasheet.

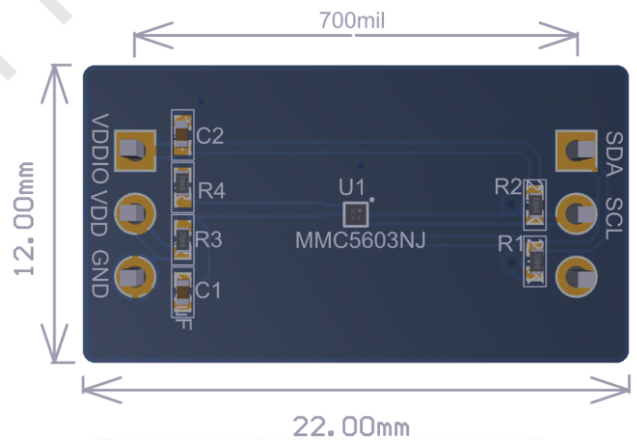
PIN DESCRIPTION

| Pin | Name | Description |
|------|-------|--------------------|
| P1-1 | VDDIO | I2C Supply Voltage |
| P1-2 | VDD3V | Power |
| P1-3 | GND | Ground |
| P2-1 | SDA | I2C SDA |
| P2-2 | SCL | I2C SCL |
| P2-3 | NC | NOT CONNECTED |



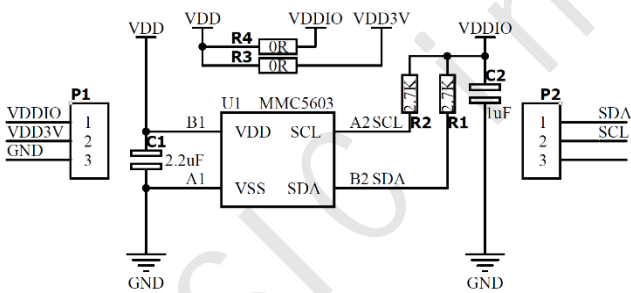
MMC560x-B

PCB OUTLINE AND CONNECTION DIMENSIONS



MMC560x-B

SCHEMATIC OF THE MMC560x-B



MMC560x-B

Information furnished by MEMSIC is believed to be accurate and reliable. However, no responsibility is assumed by MEMSIC for its use, nor for any infringements of patents or other rights of third parties, which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of MEMSIC.

MEMSIC Semiconductor (Wuxi) Co., Ltd.

No.2 Xinhuihuan Road, Xinwu District, Wuxi, Jiangsu, China
 Tel: +86-510-66616668 Fax: +86-510-66616669
 www.memsic.com